

Abstract

[0036] An integrated circuit with conductive channels connecting the bonding pads to
5 alternative surfaces of the IC chip is disclosed. Typically the channels would be formed
by reactive ion etching, passivated and then filled with copper or other conductive
material. The channels may be formed at alternative points in the wafer processing flow
depending on the requirements of the IC. Alternatively the channels may be used for heat
sinks; in this case the channel would connect a chip "hot spot" with a conductive package
10 member.

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